☐ Initial ☒ Final

Contact Date:	Implementation Date:	Alert Category:	Alert Type:	PCN #:
August 24, 2009	November 22, 2009	Discrete Semiconductors	Change of Die Attach Method	**PCN #: 1150** REV 00

TITLE

Change of Die Attach Method from Eutectic to Soft Solder.

IMPACT

None.

DESCRIPTION OF CHANGE

This PCN is to notify customers of the qualification of soft solder die attach material in order to improve overall package performance. Affected products are listed below. Full electrical characterization and high reliability testing has been completed on representative devices assembled with the soft solder die attach material in order to ensure no change to device functionality or data sheet electrical specifications before shipment to our customers.

PRODUCTS AFFECTED

ZXMHC10A07T8TA

ZXMHC3A01T8TA

ZXMHC6A07T8TA

ZXMHN6A07T8TA

WEB LINKS

Manufacturer's Notice:	http://www.diodes.com/quality/pcns/
For More Information Contact:	http://www.diodes.com/contacts/
Data Sheet:	http://www.diodes.com

DISCLAIMER

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.

PCN APPROVAL

Signatories	Name	Signature	Date
Signature of Sr. Vice President, Sales & Mktg.	**Mark KIng**		**August 24, 2009**
Signature of VP Corporate Administration	**Ed Tang**		**August 24, 2009**
Signature of VP Product Development	**Francis Tang**		**August 24, 2009**
European President & VP Sales and Mktg.	**Colin Greene**		**August 24, 2009**
European Sales Manager	**Oliver Woyke**		**August 19, 2009**
VP Business Development	**Jon Shilito**	**(approval on file)**	**August 19, 2009**